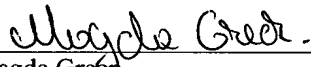


Joint Inventors

Docket No. INTEL/16651  
P16651

"EXPRESS MAIL" mailing label No.  
**EV 309992023 US**  
Date of Deposit: **August 27, 2003**

I hereby certify that this paper (or fee) is being deposited with the United States Postal Service "EXPRESS MAIL POST OFFICE TO ADDRESSEE" service under 37 CFR §1.10 on the date indicated above and is addressed to:  
Commissioner for Patents, P.O. Box 1450,  
Alexandria, VA 22313-1450

  
\_\_\_\_\_  
Magda Green

## APPLICATION FOR UNITED STATES LETTERS PATENT

# SPECIFICATION

TO ALL WHOM IT MAY CONCERN:

Be it known that We, Steven TOWLE, deceased and formerly residing at 301 W. Desert Flower Lane, Phoenix, Arizona 85045; and Daoqiang LU, a citizen of the People's Republic of China, residing at 500 N. Metro Boulevard, Apt. 1126, Chandler, Arizona 85226, have invented new and useful **OPTOELECTRONIC PACKAGES AND METHODS TO SIMULTANEOUSLY COUPLE AN OPTOELECTRONIC CHIP TO A WAVEGUIDE AND SUBSTRATE**, of which the following is a specification.

OPTOELECTRONIC PACKAGES AND METHODS TO SIMULTANEOUSLY  
COUPLE AN OPTOELECTRONIC CHIP TO A WAVEGUIDE AND SUBSTRATE

FIELD OF THE DISCLOSURE

**[0001]** The present disclosure relates generally to optical packages and, more particularly, to methods to simultaneously optically and electrically couple an optoelectronic chip to a waveguide and substrate.

BACKGROUND

**[0002]** Optical packages are typically manufactured using traditional methods that enable optoelectronic chips to communicate with other optoelectronic chips using optical signal transmissions. These traditional methods often include wire-bonding and/or flip-chip packaging processes. It is known that these optical packages are generally used in an optical communication system for transmitting and receiving high bandwidth optical signals.

**[0003]** Optical wire-bond packages and optical flip-chip packages both generally include an optoelectronic chip, a substrate and a light conducting element such as, for example, an optical fiber or a waveguide. The optoelectronic chip includes an optical element and electrically conductive contacts. The optical element, which may include a transmitter and/or receiver, is generally responsible for transmitting and/or receiving optical signals through the optical fiber and/or waveguide. The optical fiber and/or waveguide is generally adhered or attached to a substrate. Additionally, electrically conductive contacts are electrically bonded to a substrate for transmitting and/or receiving electrical signals.

**[0004]** A wire-bonding packaging process is generally carried out by individually bonding each electrically conductive contact of an optoelectronic chip to a substrate

using wire (e.g., gold wire, aluminum wire, etc.) and a wire-bonding machine. This is a time consuming process. The time required to wire-bond each optical package impacts the overall time and cost related to implementing and executing the wire-bonding package manufacturing process. In addition to limitations during the manufacturing process, wire-bonding packaging may suffer from quality and reliability issues of the wire-bond. A typical wire-bond generally has an overall length associated with a distance measured from the optoelectronic chip electrical contact to the substrate. The overall length of the wire-bond may introduce electrical inductance and capacitance, thereby creating undesirable signal bandwidth limitations and signal loss. Additionally, the wire-bond may also be susceptible to quality defects, such as, for example wire-bond breaks or wire-bond detachment. The manufacturing and performance limitations presented here have lead many chip manufacturers to turn to alternate packaging techniques such as flip-chip packaging.

**[0005]** It is known that optical flip-chip packaging is a proven method for manufacturing optical packages. A flip-chip package may include a waveguide that is adhered to a substrate and that is disposed between an optoelectronic chip and the substrate. During a bonding process, the optoelectronic chip is positioned relative to the waveguide using an active alignment process to achieve optimal light signal transmission through the waveguide, thus adding time and cost to the overall flip-chip packaging process. Additionally, the optical flip-chip packaging process generally results in an air gap disposed between the optical element and the waveguide. The air gap results in a chip-air interface and an air-waveguide interface. Fressnel losses and/or beam divergence often occur when light crosses such interfaces. Also, due to the air gap, fluxless soldering processes are generally used to form electrical bonds to

prevent flux residues from contaminating an optical path (i.e., the air gap) between the optical element and the waveguide, thereby preventing optical signal loss.

#### BRIEF DESCRIPTION OF THE DRAWINGS

[0006] Fig. 1 is a cross-sectional view of an example optical package shown prior to undergoing a soldering process.

[0007] Fig. 2 is a side view of the example optical package of Fig. 1, but showing the package after having undergone a soldering process.

[0008] Fig. 3 is a side view of the example optical package of Fig. 1, but showing the package after having undergone a defluxing process and an underfilling process.

#### DETAILED DESCRIPTION

[0009] Fig. 1 is a cross-sectional view of an example optical package 100 prior to assembly. The example optical package 100 includes a substrate 110, a waveguide 112 mounted on the substrate 110, and an optoelectronic chip 114 bonded to the substrate 110. As explained in detail below, the optoelectronic chip 114 includes an optically active area 116 (otherwise known as an optical element) which is optically coupled to the waveguide 112 via an optical solder 118. In the illustrated example, the optical element 116 is bonded to the waveguide 112 via the optical solder 118.

[0010] The substrate 110 illustrated in Fig. 1 may be implemented by any type of substrate. Thus, the substrate 110 may be formed from any desired type of material. For example, the substrate 110 may be made of an insulative, non-conductive material. The substrate 110 may also have any desired form. In the illustrated example, however, the substrate 110 is made from an Ajinomoto Build-up Film (ABF) dielectric material 120 layered on a substantially general composite substrate

122 and includes a generally planar surface conducive to flip-chip bonding and/or waveguide coupling.

**[0011]** In addition, the substrate 110 may include one or more circuits or portions of circuits. For instance, circuit lines or traces may be printed on or layered within the substrate 110. To couple circuit elements (e.g., an integrated circuit, a capacitor, an inductor, etc.) to the circuit lines or traces, the substrate 110 may further be provided with electrically conductive contacts 124. Solder bumps 126 may be deposited on one or more of the electrically conductive contacts 124 to facilitate bonding of circuit elements to the substrate 110. The solder bumps 126 may be made of any conventional and/or metallic soldering material (e.g., tin, lead, silver, etc.). A solder resistant mask (SRM) 132 may surround the electrically conductive contacts 124 and the solder bumps 126 to prevent the solder bumps 126 from bonding to anything other than corresponding solder bumps. A flux material 134 may be dispensed on the substrate solder bumps 126 to deoxidize the solder bumps 126 at elevated bonding temperatures, thus ensuring proper bonding.

**[0012]** By way of a more specific example, the substrate 110 may be implemented by a printed circuit board (PCB) substrate. The PCB may be provided with a chip-bonding surface adapted to mount a flip-chip using flip-chip on board (FCoB) bonding. In such an example, the chip-bonding surface is provided with electrically conductive contacts which are communicatively connected to electrically conductive traces printed on and/or in the PCB substrate.

**[0013]** In another example, the substrate 110 is implemented by a flex substrate such as a flexible PCB substrate. A flex substrate generally has material properties that enable bending or flexing of the substrate. The bendability of a flex substrate makes it particularly useful in mechanically demanding environments. The flex

substrate may be provided with a chip-bonding surface adapted to mount a flip-chip using flip-chip on flex (FCoF) bonding. In such an example, the chip-bonding surface includes electrically conductive contacts that are communicatively connected to electrically conductive traces which are printed on and/or in the flex substrate.

**[0014]** In still another example, the substrate 110 is implemented by a chip-package substrate such as a flip-chip package (e.g., a FCPGA package). A flip-chip package includes electrically conductive contacts on a chip-bonding surface. These contacts are communicatively connected to a second set of electrically conductive contacts on an opposite surface of the chip-package substrate. The second set of contacts may be coupled, for example, to traces on a PCB.

**[0015]** The waveguide 112 can be implemented by any type of waveguide. For example, the waveguide 112 may be implemented by a planar waveguide or an optical fiber. In the illustrated example, the waveguide 112 is a planar waveguide which may include two cladding layers (not shown), a waveguide core (not shown) disposed between the two cladding layers, and a mirror 136. The mirror 136 may be implemented in any desired manner. For example, the mirror 136 may be formed by cleaving, laser ablating or microtoming an end of the waveguide 112. The mirror 136 may also be metallized to promote reflection and reduce loss.

**[0016]** Persons of ordinary skill in the art will readily appreciate that any technique for adhering or otherwise mounting the waveguide 112 to the substrate 110 may be employed. For example, the waveguide 112 may be coupled to the substrate 110 via an adhesive layer (not shown). Furthermore, the waveguide 112 is positioned on the substrate 110 so that when an array of solder bumps 128 of the optoelectronic chip 114 are aligned to the array of solder bumps 126 of the substrate 110, the optical element 116 is aligned to the waveguide 112 to achieve optimal optical transmittance.

**[0017]** The optoelectronic chip 114 may be implemented by any desired integrated circuit having any desired purpose or functionality. In the illustrated example, the optoelectronic chip 114 is implemented by a flip-chip. The flip-chip 114 includes an optical element 116 such as a receiver, a transmitter or a transceiver. The optical element 116 may be mounted on an outer surface of the flip-chip package as shown in FIG. 1, or mounted internally of the flip-chip 114 and optically accessed via an optical aperture (not shown) such as, for example, a sealed window. The optical element 116 or optical aperture may be coupled to the top surface of the example waveguide 112 via the optical solder 118.

**[0018]** The optical solder 118, which may be a polymeric optically transparent adhesive, is dispensed on the top surface of the waveguide 112 so that, during a soldering process, the flip-chip 114 is optically bonded or optically coupled to the waveguide 112 via the optical solder 118. Material properties of the optical solder 118 make it highly compatible with the flip-chip bonding process. For example, due to its thixotropic properties, once the optical solder 118 is dispensed it remains in a fixed position until it is engaged by the flip-chip 114 during a soldering process. In another example, due to its low modulus properties after being cured, when the optical solder 118 is engaged by the flip-chip 114, the optical solder 118 will not generate structural stress and will not damage the optical element 116. Also, some optical solders 118 have a thermal curing temperature substantially equal to a melting temperature of the solder bumps 126. As a result, the optical solder may snap thermal cure during a soldering of the solder bumps 126. Furthermore, the optical solder 118 is optically transparent at a predefined wavelength allowing light of the predefined wavelength to pass between the optical element 116 and the waveguide 112.

**[0019]** In the illustrated example, at least a portion of the bottom surface of the flip-chip 114 directly engages the optical solder 118. Additionally, at least a portion of the bottom surface of the flip-chip 114 includes the solder bumps 128 that are deposited on die electrical contacts 130. Furthermore, the flip-chip 114 is coupled to the substrate 110 via the solder bumps 126, 128.

**[0020]** During a flip-chip bonding process, the flux material 134 is dispensed on the substrate solder bumps 126 and the flip-chip 114 of FIG. 1 is positioned on the substrate 110 so that each flip-chip solder bump 128 is aligned with a respective one of the substrate solder bumps 126. Additionally, the flip-chip 114 is positioned at least partially on the optical solder 118, which may be done using a pick and place machine. The optical solder 118 is, thus, at least partially disposed between the waveguide 112 and the flip-chip 114 prior to the metallic soldering to prevent the flux material 134 and any flux residue (not shown) from contaminating the optical path between the optical element 116 and the waveguide 112 during the soldering process. Furthermore, in the illustrated example, the waveguide 112 is positioned on the substrate 110 so that the mirror 136 is positioned to reflect light between the optical element 116 and the waveguide 112.

**[0021]** The soldering process associated with the flip-chip bonding process includes heating and cooling (or letting cool) the solder bumps 126, 128 so that they melt and bond to each other to form solder bonds 215 as shown in FIG. 2. More specifically, the flip-chip solder bumps 128 bond to a respectively aligned one of the substrate solder bumps 126 to form the solder bonds 215. Any or all of the substrate 110, the waveguide 112 and/or the flip-chip 114 may be heated either directly or indirectly as a result of the soldering process. Consequently, the substrate 110, the



waveguide 112 and the flip-chip 114 should be structured to withstand the temperatures associated with the soldering process without sustaining damage.

[0022] During the bonding process, melting and hardening the solder bumps 126, 128 tends to draw the flip-chip 114 and the substrate 110 together in alignment due to a surface tension of the molten solder bumps 126 and 128. This process of alignment may be referred to as solder self-alignment. Also during the soldering process, the optical solder 118 is snap thermal cured to form an optical solder joint 118 between the flip-chip 114 and the waveguide 112. As a result of the bonding process, an optical bond is formed between the flip-chip 114 and the waveguide 112 as electrical bonds are simultaneously formed between the flip-chip 114 and the substrate 110. Additionally, some residue flux material 134 is scattered throughout the example optical package 100 in the form of flux residue particles 217. During a defluxing process, a defluxing material is flooded throughout the example optical package 100 to remove the flux residue particles 217. The optical solder 118 protects the optical element 116 from being damaged by the flux residue particles 217 both before and during the defluxing process.

[0023] Following the defluxing process, an underfill 315 is disposed between the flip-chip 114 and the substrate 110 as shown in FIG. 3. The underfill 315 may comprise a non-conductive material and may be used to fill any space or spaces in the area(s) between the flip-chip 114 and the substrate 110. Because the optical solder 118 is disposed between the optical element 116 and the waveguide 112, the underfill 315 and other contaminants are prevented from entering between those elements and, thus, do not interfere with the optical coupling of the optical element 116 and the waveguide 112.

**[0024]** In addition to preventing entry of contaminants, coupling the optical element 116 and the waveguide 112 via the optical solder 118 is advantageous in several respects. For example, a gap between the flip-chip 114 and the waveguide 112 would result in a chip-air interface and an air-waveguide interface. Fresnel losses and/or beam divergence often occur when light crosses such interfaces. Therefore, because the index of refraction of the optical solder 118 substantially matches the index of refraction of the optical element 116 and the index of refraction of the waveguide 112, coupling the optical element 116 and the waveguide 112 via the optical solder 118 may reduce or eliminate Fresnel losses and beam divergence otherwise associated with chip waveguide interfaces.

**[0025]** Although certain example methods, apparatus and articles of manufacture have been described herein, the scope of coverage of this patent is not limited thereto. On the contrary, this patent covers all apparatus, methods and articles of manufacture fairly falling within the scope of the appended claims either literally or under the doctrine of equivalents.